DuPont[™] Kapton[®] E Polyimide Film

Performance demands of polyimide film as a dielectric substrate for Flexible Printed Circuits and high density interconnects have intensified since its commercial introduction in the mid 1960's. Attributes such as modulus, coefficient of thermal expansion and moisture uptake have been shown to play a significant role in the designer's challenge to maintain tighter dimensional stability targets with finer pitch circuitry. To this end, the

Modulus







specialty product Kapton[®] type E has been developed, which is available in 13, 25, 38 and 50 micron thicknesses. The excellent electrical properties and chemical etchability that have been intrinsic in HN, (VN) have been maintained in the E type. Some of the other key property comparisons are shown below (typical values as measured on 50 micron thick.)









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